



2018 IEEE International Symposium on Radio-Frequency Integration Technology August 15-17, 2018, Melbourne, Australia



First Call for Papers

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RMIT Univ., Australia

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The 2018 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2018) will be held in Melbourne, Australia on August 15-17, 2018. This conference is sponsored by the IEEE Microwave Theory and Techniques Society.

The RFIT2018 invites papers in the following technical areas:

- Device Technologies: CMOS, SOI, LDMOS, SiGe, GaAs, InP, GaN, MEMS, reliability, characterization
- Modeling and CAD: active/passive device modeling, CAD, EM simulation, co-simulation
- Packaging Technology: MCM, SiP, TSV, flip chip assembly, wire bonding, anisotropic conductive film
- Active Antennas and Passive ICs: on-chip antennas, integrated passive devices, ferrite, piezoelectric
- Frequency Generation & Conversion ICs: VCOs, PLLs, synthesizers, frequency dividers/multipliers, mixers
- Front-end RFICs: LNAs, VGAs, phase shifters, RF switches
- Power ICs: power amplifiers, linearization circuits, drivers
- Millimeter-wave and THz ICs: circuits operating at mm-wave and sub-mm-wave bands
- Analog and Mixed Signal ICs: ADC, DAC, comparators, filters, AGC/VGA
- High-Speed Data Transceivers: wireless/wireline/optical transceivers, CDRs for high-speed data links.
- RF Sensor ICs: automotive radars, wearable devices, security, biomedical and healthcare applications
- Power Transmission ICs: RFID, electromagnetic induction, wireless power transmission ICs
- Emerging ICs: power management, digital RF circuits, RF BIST, reconfigurable ICs, vehicle electronic ICs

Paper Submission:

To encourage timely reporting of the latest results and have better opportunities to expand papers for possible journal publications, prospective authors are invited to submit a 3-page manuscript (both initial submission and final manuscript, if accepted) in English and in IEEE PDF eXpress format. The manuscript should emphasize original contributions and key findings, including figures, diagrams and results from both simulations and measurements. References should be clearly cited and up-to-date. Accepted papers will be submitted to IEEE Xplore. By submitting a manuscript, the authors agree that, if accepted, at least one of the authors will make a full registration and attend the RFIT2018 to present their paper.

Important Dates:

Manuscript submission deadline:	April 02, 2018
Notification of acceptance:	May 14, 2018
Submission of final manuscript:	June 14, 2018

All must be made through the RFIT2018 website: www.rfit2018.org